

Bridge Transducer Switch

FEATURES

- Dual Matched Current Sources
- High-gain Differential Sensing Circuit
- Wide Common-mode Input Capability
- Complementary Digital Open-collector Outputs
- Externally Programmable Time Delay
- Optional Output Latch with Reset
- Built-in Diagnostic Activation
- Wide Supply Voltage Range
- High Current Heater Power Source Driver

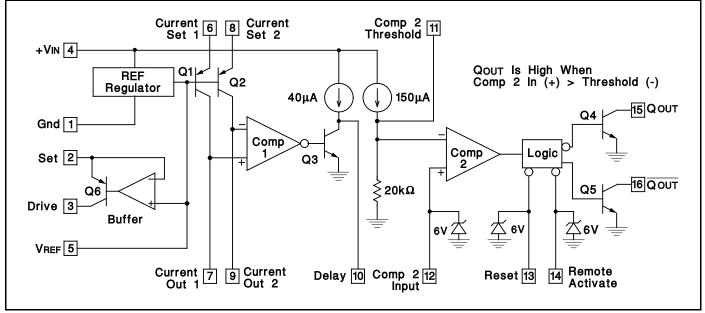
UC3704 COMPATIBLE SENSORS

DESCRIPTION

This integrated circuit contains a complete signal conditioning system to interface low-level variable impedance transducers to a digital system. A pair of matched, temperature-compensated current sources are provided for balanced transducer excitation followed by a precision, high-gain comparator. The output of this comparator can be delayed by a user-selectable duration, after which a second comparator will switch complementary outputs separately activated for diagnostic operation and has an optional latch with external reset capability. An added feature is a high current power source useful as a heater driver in differential temperature sensing applications. The UC3704 is designed for 0°C to +70°C environments.

SENSOR TYPE	ACTIVATION SOURCE								
	Temperature	Pressure	Force	Position	Displacement	Velocity	Shock		
Thermistor	Х					Х			
Sensistor	Х					Х			
Thermocouple	Х								
Semiconductor	Х	Х	Х						
Photo Voltaic				Х	Х	Х			
Photo Resistive				Х	Х	Х			
Strain Gage		Х	Х	Х	Х	Х	Х		
Piezoelectric		Х	Х		Х	Х	Х		
Magneto Resistive				Х	Х				
Inductive				Х	Х	Х	Х		
Hall Effect				Х	Х				
Capacitive							Х		

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Supply Voltage (+VIN). 40V Output Current (each output) 50 mA Buffer Power Source Current 200mA Comparator 1 Inputs. -0.5V to VREF Comparator 2 Inputs. 0 to 5.5V Remote Activation and Reset Inputs 0 to 5.5V Power Dissipation at TA = 25°C 1000mW Operating Junction Temperature -55°C to +150°C Storage Temperature Range -65°C to +150°C Lead Temperature (Soldering, 10 Seconds) +300°C Note: Unless otherwise specified, all voltages are with respect to ground (Pin 1). Currents are positive into, negative out of the specified terminal. Consult Packaging section of Databook for thermal Consult Packaging section of Databook for thermal
terminal. Consult Packaging section of Databook for thermal imitations and considerations of package.
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CONNECTION DIAGRAM

DIL-16 (TOP VIEW) J or N Package							
	\square	1					
Gnd 1		16	QOUT				
Buffer Set 2		15	QOUT				
Buffer Drive 3		14	Rem. Act.				
+VIN 4		13	Reset				
VREF 5		12	Comp 2 In				
Cur. Set 1 🧕		11	Comp 2 Thres.				
Cur. Out 1 🔽		10	Delay				
Cur. Set 2 8		9	Cur. Out 2				
		J					

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for $TA = 0^{\circ}C$ to +70°C for the UC3704: VIH = 15V, TA =TJ.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Power Inputs					-
Supply Voltage Range		4.2		36	V
Supply Current	VIN = 36V		5	10	mA
Reference Section (with respect to VIN)		-			-
Vref Value Vin - Vref	$T_J = 25^{\circ}C$	2.1	2.2	2.3	V
VREF Temperature Coefficient	Note 1	-1	-2	-3	mV/°C
Line Regulation	$\Delta VIN = 4.2$ to 25V		2	10	mV
Load Regulation	$\Delta IO = 0$ to 4mA		2	10	mV
Short Circuit Current	VIN = 36V, VREF = VIN or Ground			±25	mA
Current Source (Q1 and Q2)					
Output Current (Note 2)	Current Set = 10μA	-9	-9.5	-10	μA
	Current Set = 200µA	-180	-195	-200	μA
Output Offset Current	$RE6 = RE8 = 20k\Omega$		0	±1	μA
Comparator One					
Input Offset Voltage			±1	±4	mV
Input Bias Current			-100	-300	nA
Input Offset Current				±60	nA
CMRR	VCM = 0 to 12V	60	70		dB
Voltage gain	RL>150kΩ	70	85		dB
Delay Current Source		34	40	52	μA
Output Rise Time	Overdrive = 10mV, CD = 15pF, TJ = 20°C		2		V/µs

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for TA = 0°C to +70°C for the UC3704: VIH = 15V, TA =TJ.

PARAMETER	TEST CO	MIN	TYP	MAX	UNITS	
Comparator Two (QOUT and QOUT)	ł		•	I.		-
Threshold Voltage		2.2	3.0	3.8	V	
Threshold Resistance	To Ground		14	20	24	kΩ
Input Bias Current	VIN (Pin 12) = 5V			1	3	μA
Remote Activate Current	Pin 14 = 0V			0.2	0.5	mA
Reset Current	Pin 13 = 0V		0.2	0.5	mA	
Remote Activate Threshold	TA = 25°C	0.8	1.2		V	
Reset Threshold	$T_A = 25^{\circ}C$	0.8	1.2		V	
Output Saturation	IOUT = 16mA		0.2	0.5	V	
	10UT = 50mA		0.7	2.0	V	
Output Leakage	Vout = 40V	Vout = 40V		0.2	10	μA
Output Response	Comp. Overdrive = 1V	Turn-on		0.4		μs
	RL = 5k to VIN	Turn-off		1.0		μs
Buffer						
Set Voltage (VIN -Vs)	TJ = 25°C, IS = 100mA	1.9	2.1	2.3	V	
Drive Current	TJ = 25°C, Rs = 200Ω, VD = 0V		90	100	120	mA

RE

Note 1: Parameter guaranteed by design, not tested in production.

Note 2: Collector output current = $\frac{VIN - VREF - VBE}{2} \approx \frac{1.5V}{2}$ RE

APPLICATIONS INFORMATION

Sensor Section

The input portion of the UC3704 provides both excitation and sensing for a low-level, variable impedance transducer. This circuitry consists of a pair of highly matched PNP transistors biased for operation as constant current sources followed by a high gain precision comparator.

The reference voltage at the bases of the PNP transistors has a TC to offset the base-emitter voltage variation of these transistors resulting in a constant voltage across the external emitter resistors and correspondingly constant collector currents for balancing, offsetting, or to provide unique temperature characteristic.

With the PNP transistor's optimum current ranging from 10 to 200µA, and the common-mode input voltage of the comparator usable from ground to (VIN - 3V), a wide range of transducer impedance levels is possible.

The sensor comparator has a current source pull-up at the output so that an external capacitor from this point to

ground can be used to provide a programmable delay before reaching the second comparator's threshold. The low-impedance on-state of Comp 1's output provides quick reset of this capacitor. This programmable delay function is useful for providing transient protection by requiring that Comp 1 remain activated for a finite period of time before Comp 2 triggers. Another application is in counting repetitive pulses where a missing pulse will allow Comp 1's output to rise to Comp 2's threshold. This time delay function is:

$$Delay = \frac{Comp2 \ Threshold}{Delay \ Current} X \ C_D \approx 175 ms/\mu F$$

If hysteresis is desired for Comparator 1, it may be accommodated by applying positive feedback from the delay terminal to the non-inverting input on Pin 7. This will aid in providing oscillation-free transitions for very slowly changing inputs.

APPLICATIONS INFORMATION (cont.)

Output Section

The output portion of the UC3704 is basically a second comparator with complimentary, open-collector outputs. This comparator has a built-in, ground-referenced threshold implemented with a high-impedance current source and resistor so that it may be easily overridden with an external voltage source if desired. Comp 2's input transistors are NPN types which require at least 1V of common-mode voltage for accurate operation and should not see a differential input voltage greater than 6V.

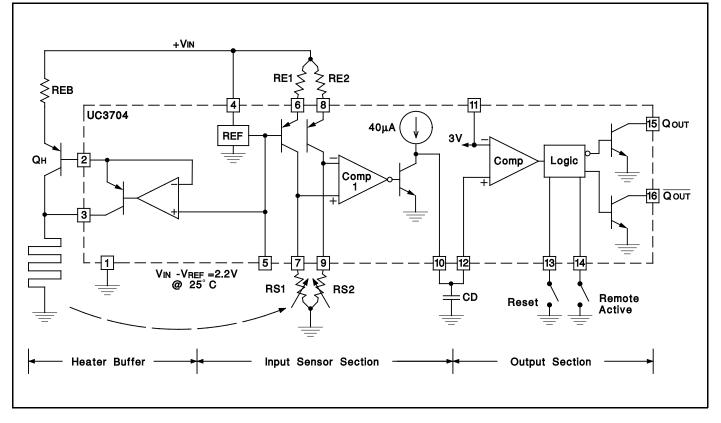
For diagnostic or latching purposes, the output logic is equipped with a Remote Activate and Reset function. These pins have internal pull-ups and are only active when pulled low below a threshold of approximately 1V. A low signal at the Remote Activate Pin causes the outputs to change state in exactly the same manner as if Comp 2's input is raised above the threshold on Pin 11. If Pin 16 is connected to Pin 14, positive feedback results and the outputs will latch once triggered by Comp 2's input. Pulling the Reset terminal low overrides the Remote Activate Pin releasing the latch.

Reference Buffer

This circuit is designed to provide up to 100mA to drive a high current external PNP transistor useful for powering a heater for differential temperature measurements. Care must be taken that power dissipation in Q6 does not cause excessive thermal gradients which will degrade the accuracy of the sensing circuitry.

Using a heating element attached to a temperature sensitive resistor, RS1, in one leg of the input bridge implements a flow sensor for either gasses or liquids. As long as there is flow, heat from the element is carried away and the sensor voltage remains below threshold. Using an identical sensor, RS2, without a heater to establish this threshold compensates for the ambient temperature of the flow.

TYPICAL APPLICATION FOR MONITORING LIQUID OR GAS FLOW



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UC3704J	OBSOLETE		UTR		TBD	Call TI	Call TI
UC3704N	OBSOLETE		UTR		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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